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U.S. PATENT DOCUMENTS

EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
RG	A1	5,467,883	11/21/95	Frye et al.	216	60	11/27/93
	A2	5,559,690	9/24/96	Keeler et al.	364	164	9/16/94
	A3	5,654,903	8/5/97	Reitman et al.	364	551.01	11/7/95
	A4	5,740,033	4/14/98	Wassick et al.	364	149	10/13/92
	A5	6,268,226	7/31/01	Angell et al.	438	16	6/30/99

FOREIGN PATENT DOCUMENTS

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RG	B1	WO 01/57605	8/9/01	WO	G05B	13/04	1/11/01	N	Y
RG	B2	DE196 37 917 A1	3/19/98	DE	G05B	13/04	9/17/96	Y	

OTHER ART, JOURNAL ARTICLES, ETC.

EXAM. INIT.		OTHER DOCUMENTS: (Including Author, Title, Date, Relevant Pages, Place of Publication)
RG	C1	Card et al., "Dynamic Neural Control for Plasma Etch Process," <u>IEEE Transactions on Neural Networks,</u> (1997).
	C2	Dillon et al., "Guest Editorial Everyday Applications of Neural Networks," <u>IEEE Transactions on Neural Networks,</u> 8:4 (1997).
	C3	Hatzipantelis et al., "Comparing Hidden Markov Models with Artificial Neural Network Architectures for Condition Monitoring Applications," <u>Artificial Neural Networks,</u> 26-28, Conference Publication No. 409 (June 1995).
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